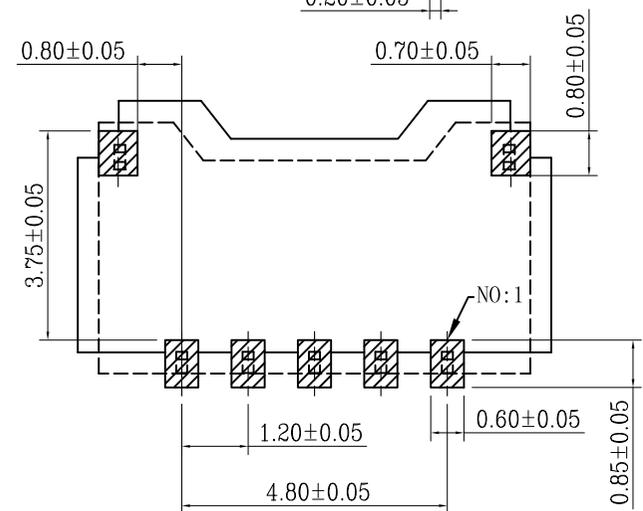
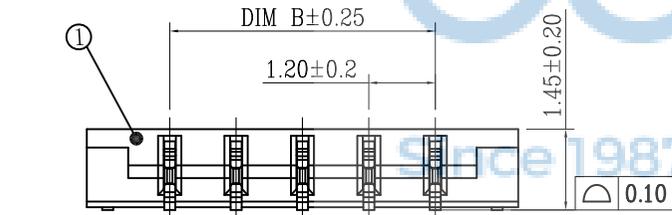
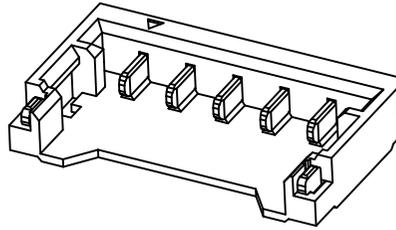
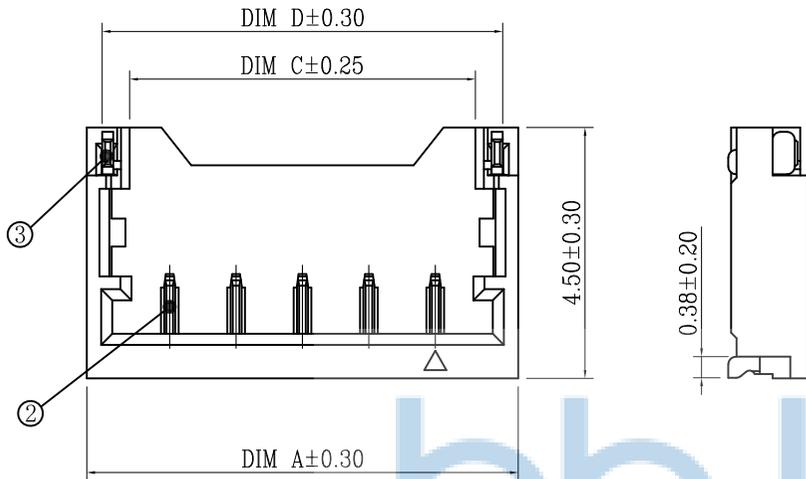


REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

技术指标:

1. 塑件表面应光洁、无毛边、无明显收缩、缺陷、裂纹等现象。
2. 温度范围: $-25^{\circ}\text{C} \sim 85^{\circ}\text{C}$ 。
3. 额定电压: 50V AC, DC。
4. 耐电压: 500V AC/minute。
5. 接触电阻: $\leq 20\text{m}\Omega$ 。
6. 绝缘电阻: $\geq 100\text{M}\Omega$ 。
7. 额定电流: 1.5A AC, DC。



适用线路板 (PCB LAYOUT)



序号	品名	材质
①	1.2 Pitch B型胶芯	LCP UL94V-0 黑色
②	1.2 Pitch B型端子	铜合金/表面镀锡/镀金
③	1.2 Pitch B型焊片	铜合金/表面镀锡/镀金

CKT	DIM A	DIM B	DIM C	DIM D
2	4.20	1.20	2.65	3.64
3	5.40	2.40	3.85	4.84
4	6.60	3.60	5.05	6.04
5	7.80	4.80	6.25	7.24
6	9.00	6.00	7.45	8.44
7	10.20	7.20	8.65	9.64
8	11.40	8.40	9.85	10.84
9	12.60	9.60	11.05	12.04
10	13.80	10.80	12.25	13.24
11	15.00	12.00	13.45	14.44
12	16.20	13.20	14.65	15.64

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PDWG.NO: 0456-1

DR. TSP

深圳市步步精科技有限公司

NAME: Molex 针座 B型 1.20-3P 卧贴 黑色 镀金GF

APPD. JM_Zheng

CHKD. LYX

PJ. NO.: 143-011-000002-X3G

SIZE: A4

FINISH: SEE NOTES

SCALE: N/A

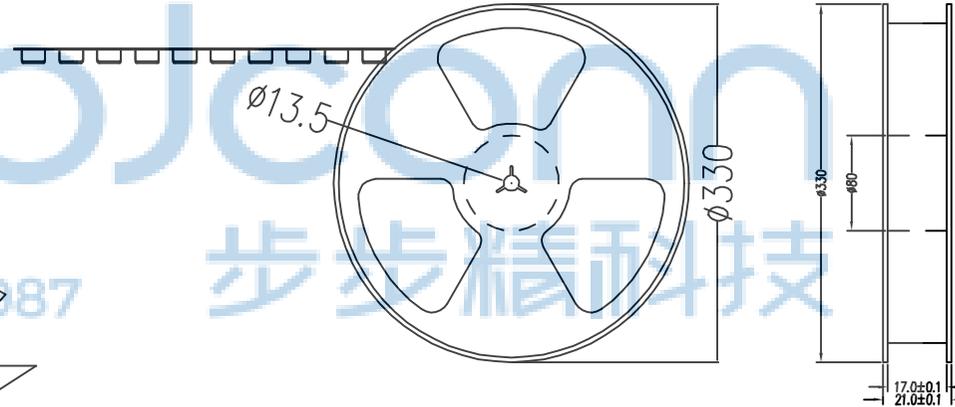
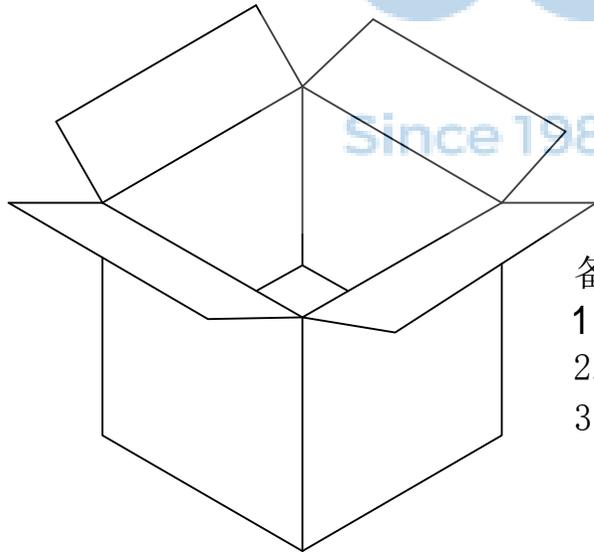
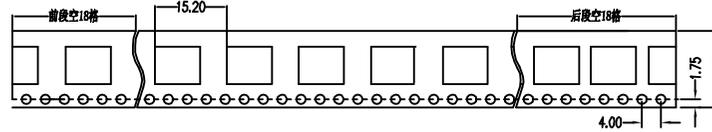
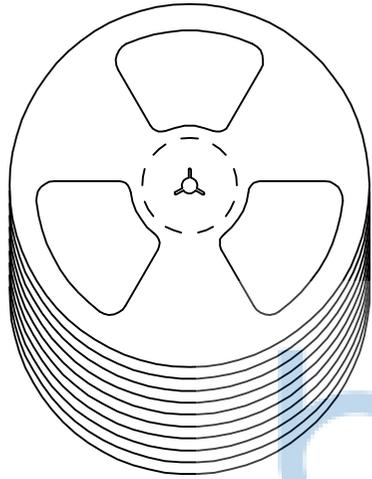
MAT'L.: SEE NOTES

REV.: A0

UNIT: mm

PAGE: 1/2

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



备注:

1. 包装数量：4500/PCS/卷，10卷/箱
2. 包装袋长度：每卷前后各空10-20个空格，中间包装。
3. 材质：
载体：聚丙烯（PS），
上带：聚乙烯（PET），
卷盘：聚苯乙烯。

纸箱规格：345*345*23MM

纸箱规格：345*345*35MM

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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X': ±3' X'': ±2' XX': ±1'	
APPD.	JM_Zheng	NAME: Molex 针座 B型 1.20-3P 卧贴 黑色 镀金GF	
CHKD.	LYX	PJ. NO.: 143-011-000002-X3G	
DR.	TSP	SIZE: A4 DRW NO.:	
PDWG.NO: 0456-1		FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/2	